WHAT IS CLAIMED IS:

- An integrated active rectifier module comprising;
 a base plate;
 a plurality of substrates attached to said base plate;
 power elements for an active rectifier mounted on one of said substrate;
 elements for a voltage regulator mounted on another one of said substrates; and elements for driving said power elements mounted on another one of said substrates.
 - 2. An integrated active rectifier module according to claim 1 further comprising, a first lead frame, and a first lead frame support, said lead frame being supported on said first lead frame support over said plurality of substrates.
 - 3. An integrated active rectifier module according to claim 2, wherein said lead frame support is attached to said base plate.
 - 4. An integrated active rectifier module according to claim 2, wherein said lead frame support surrounds said plurality of substrate.
 - 5. An integrated active rectifier module according to claim 1, further comprising a second lead frame, and a second lead frame support, said second lead frame being supported above said first lead frame by said second lead frame support.
 - 6. An integrated active rectifier module according to claim 5, wherein said first lead frame is used to connected a phase of a stator to said active rectifier and said second lead frame serves as an output lead frame for said active rectifier.

- 7. An integrated active rectifier module according to claim 1, wherein said substrates are attached to said base plate by a flexible adhesive.
- 8. An integrated active rectifier module according to claim 1, further comprising a heatsink in thermal contact with said base plate.
- 9. An integrated active rectifier module according to claim 1, further comprising a conductive block on at least one of said substrates, said conductive block extending above said substrate.